		DESCRIPTION O		BY	CHKD				DESCRIPT			BY			DATE
APPI							Δ								
							Δ								
DAT	LICA	BLE STANDAR	D						•					1	
DΛT	Operating Temperature Operating Hu		ange -55 C to +105 C (Note1) Te							emperature Range					-,
RATING		Range		20% to 80% (Note2) Ra						ange 40% to 70% (N					
		Applicable Conr							Voltage						
		Applicable Contact		DF51K-22SC(A)/SCF(A) (###) DF51K-2428SC(A)/SCF(A) (###) DF51K-30SC(A)/SCF(A) (###)					Current	AWG 30: 0.5A AWG 2 AWG 26: 1.5A AWG 22-24: 2A					1A
					S	SPECI	FIC	ATIO	NS						
		ITEM		TE	ST ME	THOD				REQUIR	EMENT	S		QT	A
			1									-		<u> </u>	<u> </u>
		mination	Visually and	bv mea	suring ir	nstrumen	t.							0	
larkin	ng		Confirmed v		0				 According to 	According to drawing.					
	0			s										-	
					C ar 10	000-)			30 mΩ MAX						Τ_
Contact Resistance Millivolt Level Method			20mV MAX, 1mA (DC or 1000Hz).						30 ms2 IVIAA.	50 MS2 MAA.					-
		esistance	500 V DC.						1,000 MΩ M	1,000 MΩ MIN.					t.
/oltag	ge Proo	of	650 V AC for 1 min.						No flashover	No flashover or breakdown.					\vdash
														0	_
			1								0 0 1441	,		Т	Τ-
Mechanical Operation (Sn Plating										①Contact resistance: 30mΩ MAX ②No damage, crack or looseness of parts.					
Mechanical Operation (Au Plating)			50 times insertion and extraction.						\sim	(1)Contact resistance: $30m\Omega$ MAX (2)No damage, crack or looseness of parts.					
Mating and unmating Force (Sn Plating) Mating and unmating Force									-	©Extraction Force: 7.2N MIN					
									-						T.
		(Au Plating))						②Extraction	②Extraction Force: 7.0N MIN					
'ibrati	ion		Frequency 10 to 55 Hz, single amplitude 0.75 mm,						(1)No electrical discontinuity of 1 μ s.					0	
hock				10 cycles for 3 direction.					②No damage, crack or looseness of parts.						_
nock			Acceleration 490 m/s^2 duration of pulse 11 ms at 3 times for 3 directions.						3					0	-
Contact extraction force			Pull out the	cable at	fter hou	sing fixat	ion.		11.8N MIN					0	1-
ENV	IRON	MENTAL CH	ARACTER	ISTIC	S				•						
)amp	Heat		Exposed at 4	10 ± 2	°C , hur	nidity 90	to 95	%, 96 h.	1 Contact re	esistance: 30	0 mΩ MA	X.		0	Τ
(Steady State		(After leaving the room temperature for 1 to 2h.)						-	\textcircled{O} Insulation resistance: 500M Ω MIN. ONo damage, crack or looseness of parts.					-	
Rapid Change of			Temperature $-55 \ ^{\circ}C \rightarrow +105 \ ^{\circ}C$						①Contact re					1	\vdash
Temperature			Time $30 \text{min} \rightarrow 30 \text{min}$ Under 5 Cycles. (The transferring time of the tank is 2 to 3 MIN) (After leaving the room temperature for 1 to 2h.)						s. ②Insulation	\textcircled{O} Insulation resistance: 1,000M Ω MIN. ONo damage, crack or looseness of parts.					
									③No damag						
rv Hi	/ Heat Exposed at 105±2 °C, 96h					LII./		4				0	┢.		
old					—	1					+				
lemar	rks		at	50 <u>-</u> 1	2 0, 00									0	1
lote 1 lote 2	1: Inclu 2: No c 3: Appl	ide the temperature condensing y to the condition of idity reasons in condition	of long term s	torage f		-		-	b on board, afte	er pcb board	, operatir	ng temp	perature	e and	
	num	idity range is applie		storage	uuririg		DRAW		DESIGNED	CHECKE		PROVE		RELEA	<u> </u>

			DRAW	'N	DESIGN	ED	CHECKED	APPROVED	RELEASED		
			J.S CH	IOI	J.S CHC		S.M.LIM	T.S KANG	ENG 20, 02, 13		
			17.12.	22	17.12.22		17.12.22	17.12.22	DEPT		
Unless otherwise specified, refer to IEC 60512.											
NOTE QT: QUALIFICATION TEST AT: ASSURANCE TEST O: APPLICABLE TEST											
						PART	ΓNO.				
HIROSE KOREA CO.,LTD. SPECIFI			CATION SHEET			DF51K-28DS-2C (800)					
CODE NO.(OLD) DRAWING NO.			CO						1 /		
CL ELC4-632491					CL 6652-0037-9-800			1			